

## 46 - 52 GHz Low Noise Amplifier with Adjustable Gain Control

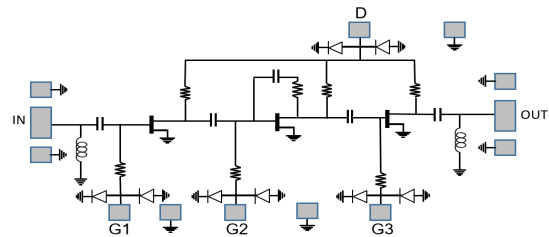
### GaAs Monolithic Microwave IC

#### Description

The CHA2353-99F is a three stage monolithic Low Noise Amplifier, producing 24dB linear gain with 30dB Adjustable Gain Control (AGC) and 3.5dB Noise Figure in the frequency band 46-52GHz. It includes ESD protections on each RF access and DC pads.

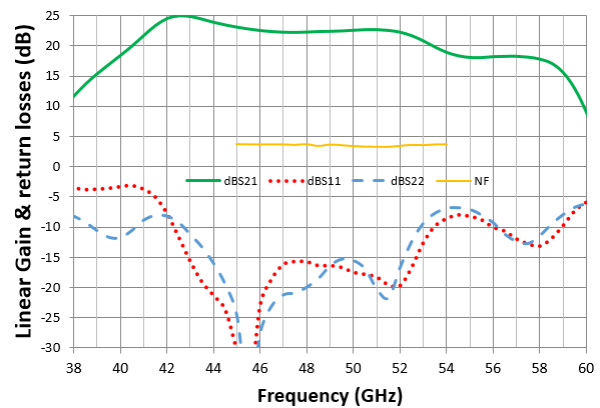
This amplifier is designed for a wide range of applications, from Commercial to Space communication systems.

It is manufactured with a GaAS pHEMT process successfully evaluated for Space and is available in bare die.



#### Main Features

- Frequency band: 46-52GHz
- 3.5dB Noise Figure
- 24dB small signal gain
- 30dB Adjustable Gain Control
- P<sub>1dB</sub>: 9dBm
- P<sub>sat</sub>: 11dBm
- OIP3: 20dBm
- Typical DC bias: V<sub>d</sub> = 3.3V@I<sub>d</sub> = 55mA
- Chip size 1.97x1.17x0.07mm



Typical S parameters and Noise Figure

#### Main Electrical Characteristics

T<sub>backside</sub> = +25°C, V<sub>d</sub> = +3.3V, VG(G1=G2=G3) set in order to get I<sub>dq</sub> = 55mA (≈0V)  
(T<sub>backside</sub> : Die backside temperature)

Symbol	Parameter	Min	Typ	Max	Unit
Frequency	Frequency range	46		52	GHz
Gain	Small signal Gain		24		dB
NF	Noise Figure		3.5		dB
I <sub>d</sub>	Drain bias current		55		mA

## Electrical Characteristics

$T_{\text{backside}} = +25^{\circ}\text{C}$ ,  $V_d = +3.3\text{V}$ ,  $V_G$  ( $G1=G2=G3$ ) set in order to get  $I_{dq} = 55\text{mA}$  ( $\approx 0\text{V}$ )

( $T_{\text{backside}}$  : Die backside temperature)

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	46		52	GHz
Gain	Small Signal Gain		24		dB
NF	Noise Figure		3.5		dB
IRL	Input return loss		-13		dB
ORL	Output return loss		-15		dB
Gain ctrl	Gate control voltage to gain sensitivity		30		dB
IP-1dB	Input power at 1dB gain compression		-13		dBm
OP-1dB	Output power at 1dB gain compression		9		dBm
$V_d$	Drain bias voltage		3.3		V
$I_d$	Drain bias current		55		mA

These values are representative of on-board measurements as defined on the drawing in paragraph "Evaluation board".

## Absolute Maximum Ratings <sup>(1)</sup>

$T_{\text{backside}} = +25^{\circ}\text{C}$

Symbol	Parameter	Values	Unit
$V_d$	Drain bias voltage	4.2V	V
$V_g$	Gate bias voltage	-2 to +0.4	V
$P_{in}$	Maximum peak input power overdrive	-2	dBm
$T_j$	Junction temperature	175	$^{\circ}\text{C}$

<sup>(1)</sup> Operation of this device above anyone of these parameters may cause permanent damage.

## Recommended Operating Range <sup>(2), (3)</sup>

$T_{\text{backside}} = +25^{\circ}\text{C}$

Symbol	Parameter	Values	Unit
$V_d$	Drain bias voltage	3 to 4	V
$V_g$	Gate bias voltage	-0.5 to +0.1	V
$P_{in}$	Input power range	-20 to -5	dBm

<sup>(2)</sup> Electrical performances are defined for specified test conditions

<sup>(3)</sup> Electrical performances are not guaranteed over all recommended operating conditions

## Typical Bias Conditions

$T_{\text{backside}} = +25^{\circ}\text{C}$

Symbol	Parameter	Value	Unit
VG1, VG2, VG3	Gate bias voltage tuned for $I_d = 55\text{mA}$	0	V
VD	Drain bias voltage	3.3	V

### “Power ON” sequence

1. Ground the device
2. Set the gate voltage close to  $V_{\text{pinch-off}}$  ( -1.5V)
3. Apply the drain voltage  $V_d$  (typically +3.3V)
4. Increase  $V_g$  up to quiescent bias drain current  $I_d$
5. Apply RF signal

### “Power OFF” sequence

1. Turn off RF signal
2. Decrease the gate voltage to -1.5V
3. Decrease the drain voltage to 0V
4. Turn off  $V_d$  supply
5. Turn off  $V_g$  supply

## Device thermal performance

All figures given in this section are obtained assuming the chip backside is only cooled down by the conduction through the test board (no convection mode is considered).

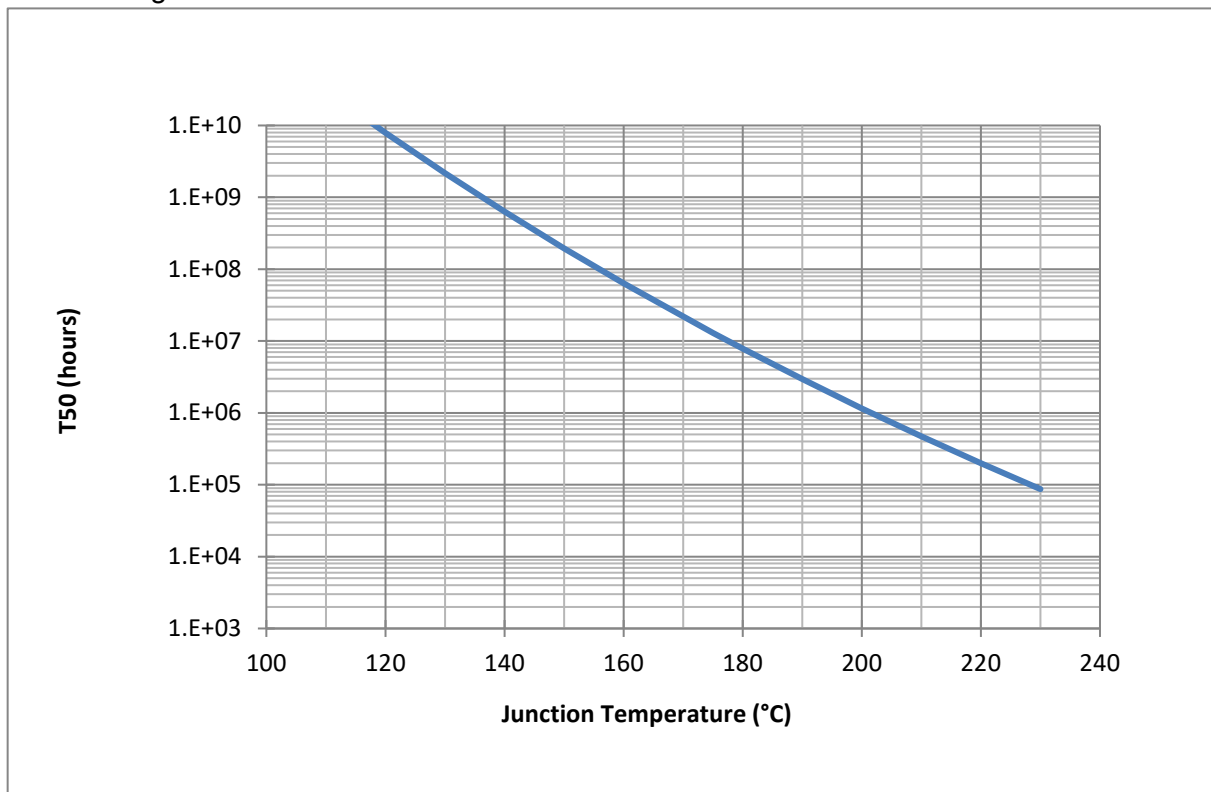
The temperature is monitored at the chip backside ( $T_{backside}$ ).

The system maximum temperature must be adjusted in order to guarantee that  $T_J$  remains below the maximum value specified in the Recommended Operating Range table.

The system PCB must be designed to comply with this requirement.

Parameter	Biasing conditions	Tjunction (°C)	R <sub>TH</sub> (°C/W)	T50 (hours)
R <sub>TH</sub> <sup>(1)</sup> Thermal Resistance ( Junction to Case)	Vd = 3.3V Id = 75mA P <sub>diss</sub> = 0.25W	143	230	4.4x10 <sup>8</sup>
	Vd = 3.3V Id = 55mA P <sub>diss</sub> = 0.18W	130	250	2.2x10 <sup>9</sup>

<sup>(1)</sup> Assuming 85° T<sub>backside</sub>

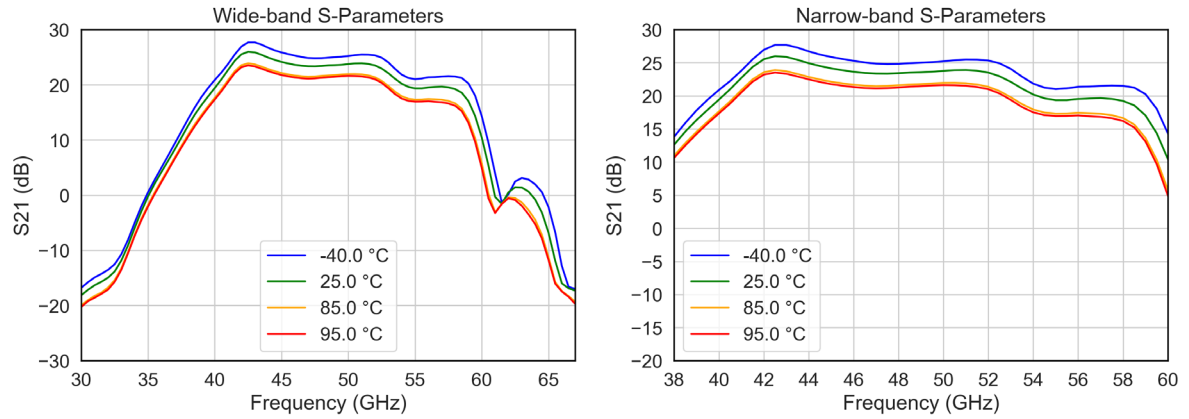


Typical on Board Measurements

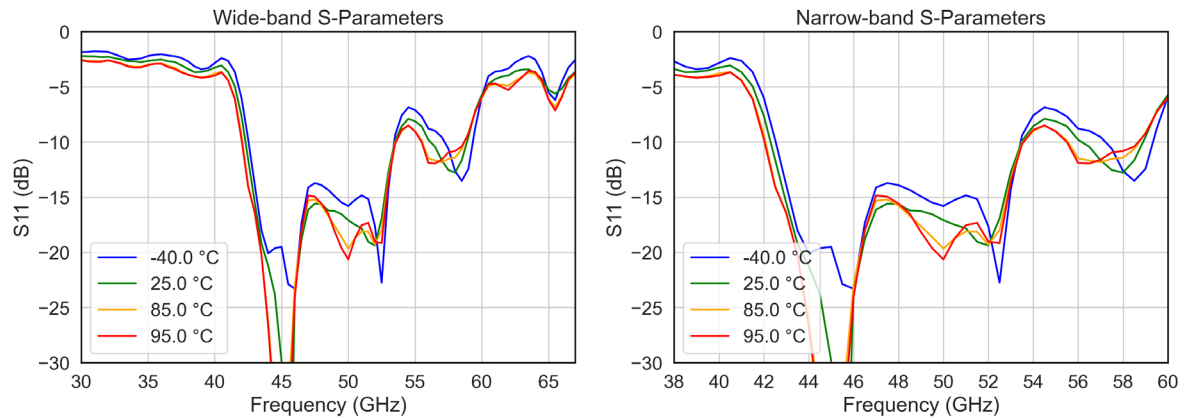
Test conditions :  $T_{backside} = -40^{\circ}\text{C}/+25^{\circ}\text{C}/85^{\circ}\text{C}/95^{\circ}\text{C}$ ,  $V_d = 3.3\text{V}$ ,  $I_d = 55\text{mA}$

Board losses are de-embedded. Measurements are given in the die access plans.

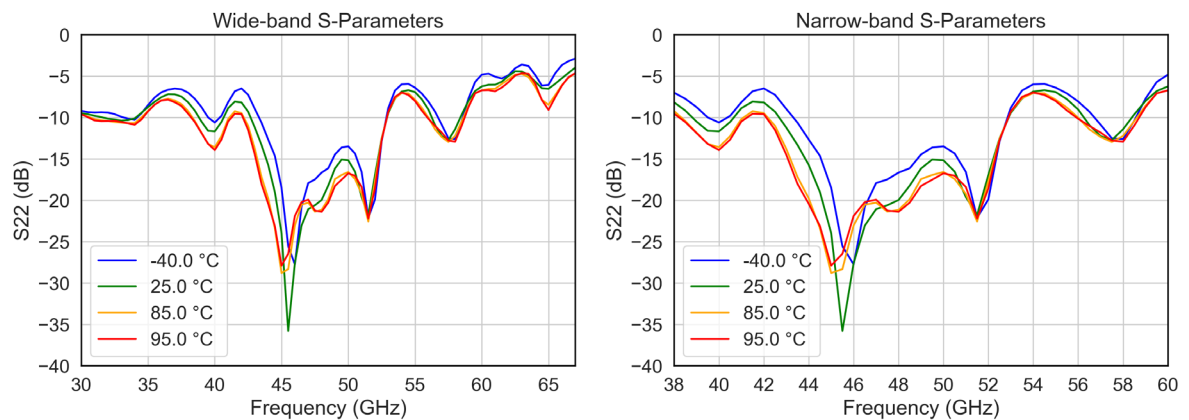
Linear Gain vs. Frequency & Temperature



Input Return Loss vs. Frequency & Temperature



Output Return Loss vs. Frequency & Temperature

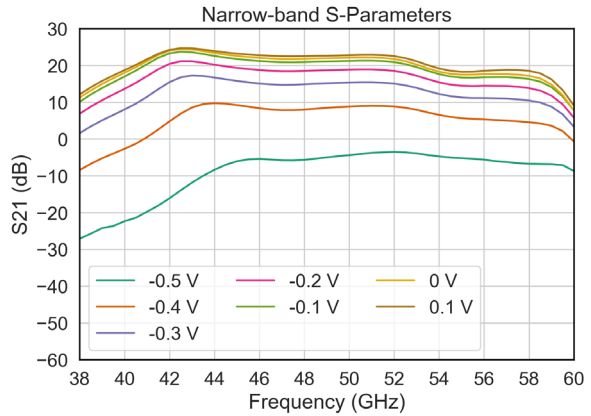
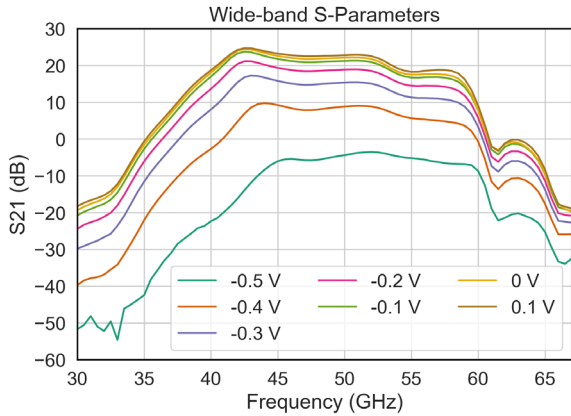


## Typical on Board Measurements

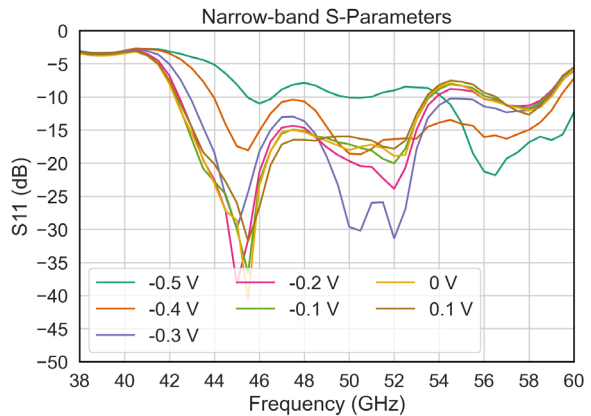
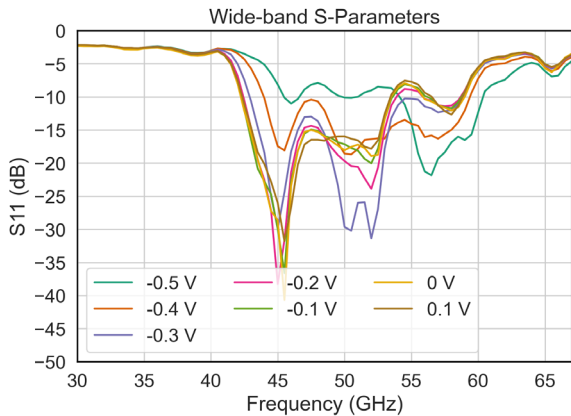
**Test conditions :**  $T_{\text{backside}} = +25^{\circ}\text{C}$ ,  $V_d = 3.3\text{V}$ ,  $V_g = -0.5$  to  $+0.1\text{V}$

Board losses are de-embedded. Measurements are given in the die access plans.

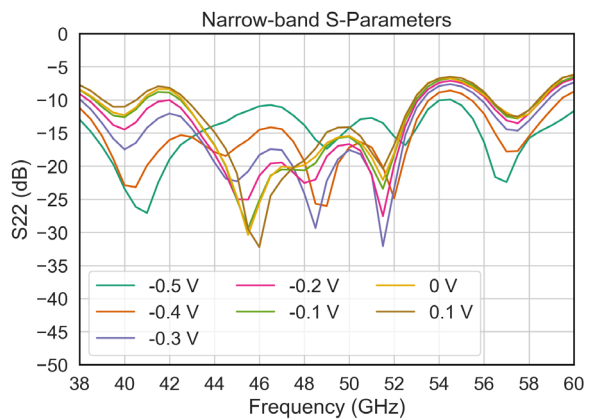
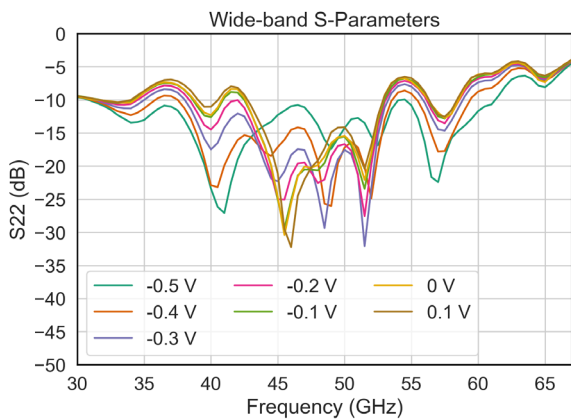
### Linear Gain vs. Frequency & Gate voltage



### Input Return Loss vs. Frequency & Gate voltage



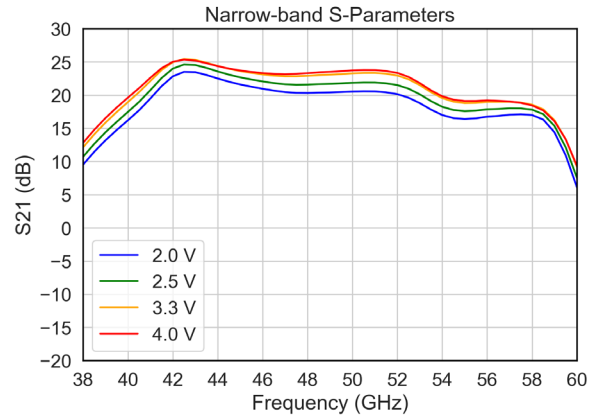
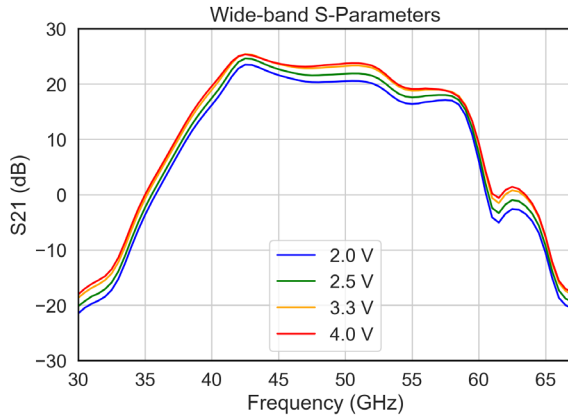
### Output Return Loss vs. Frequency & Gate voltage



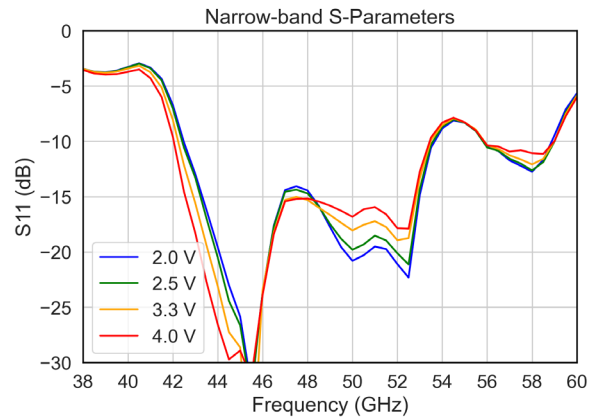
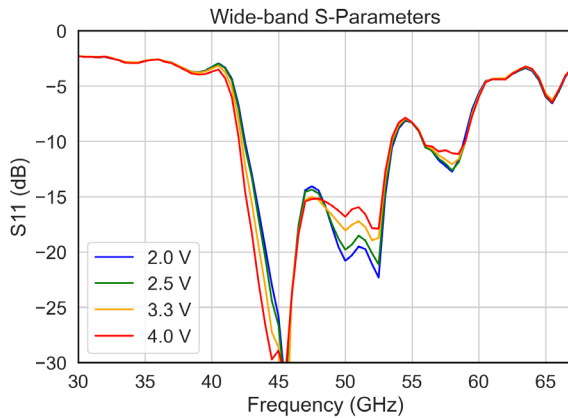
Typical on Board Measurements

Test conditions :  $T_{backside} = +25^{\circ}\text{C}$ ,  $V_d = 2/2.5/3.3/4\text{V}$ ,  $I_d = 40/45/55/65\text{mA}$  ( $V_g \approx 0\text{V}$ )  
 Board losses are de-embedded. Measurements are given in the die access plans.

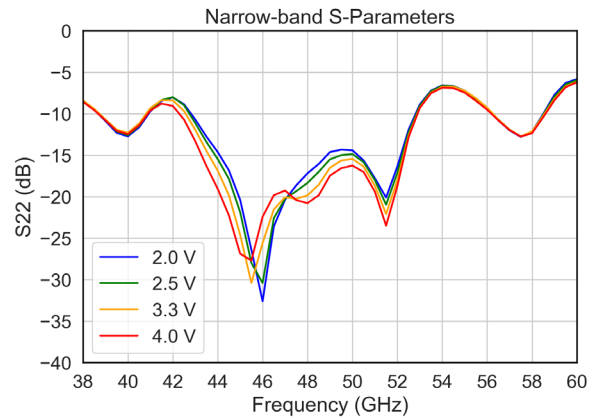
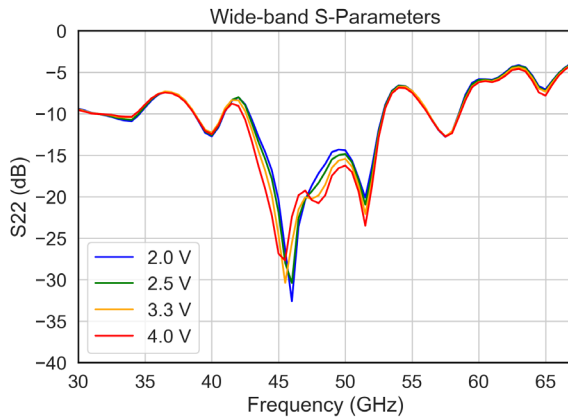
Linear Gain vs. Frequency & Drain voltage



Input Return Loss vs. Frequency & Drain voltage



Output Return Loss vs. Frequency & Drain voltage

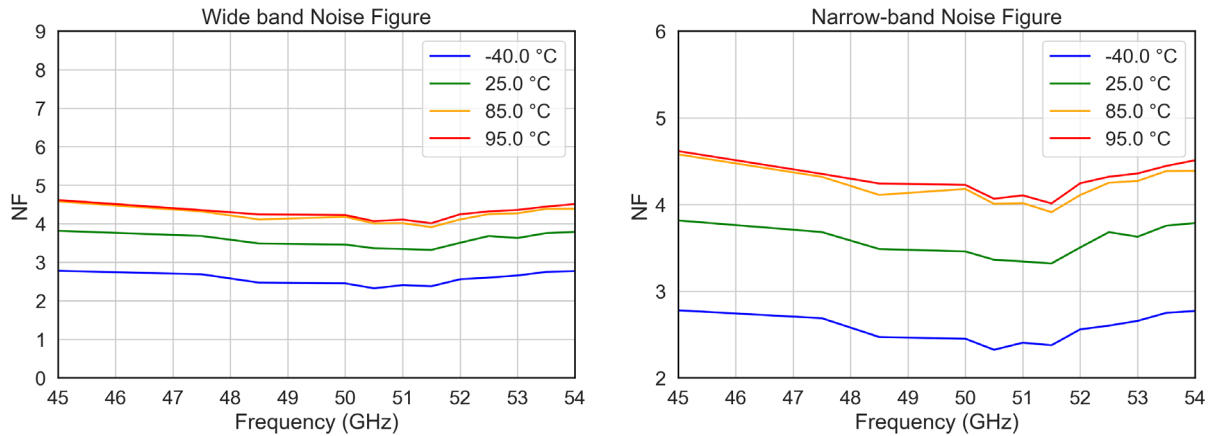


## Typical on Board Measurements

**Test conditions :**  $T_{\text{backside}} = -40^{\circ}\text{C}/+25^{\circ}\text{C}/85^{\circ}\text{C}/95^{\circ}\text{C}$ ,  $V_d = 3.3\text{V}$ ,  $I_d = 55\text{mA}$

Board losses are de-embedded. Measurements are given in the die access plans.

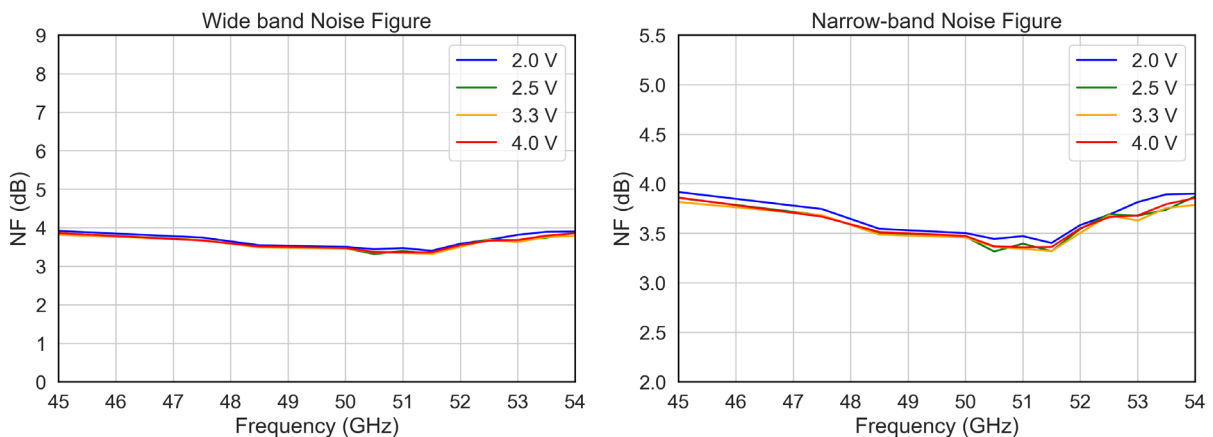
### Noise Figure vs. Frequency & Temperature



**Test conditions :**  $T_{\text{backside}} = +25^{\circ}\text{C}$ ,  $V_d = 2/2.5/3.3/4\text{V}$ ,  $I_d = 40/45/55/65\text{mA}$

Board losses are de-embedded. Measurements are given in the die access plans.

### Noise Figure vs. Frequency & Drain voltage & Tbackside = 25°C

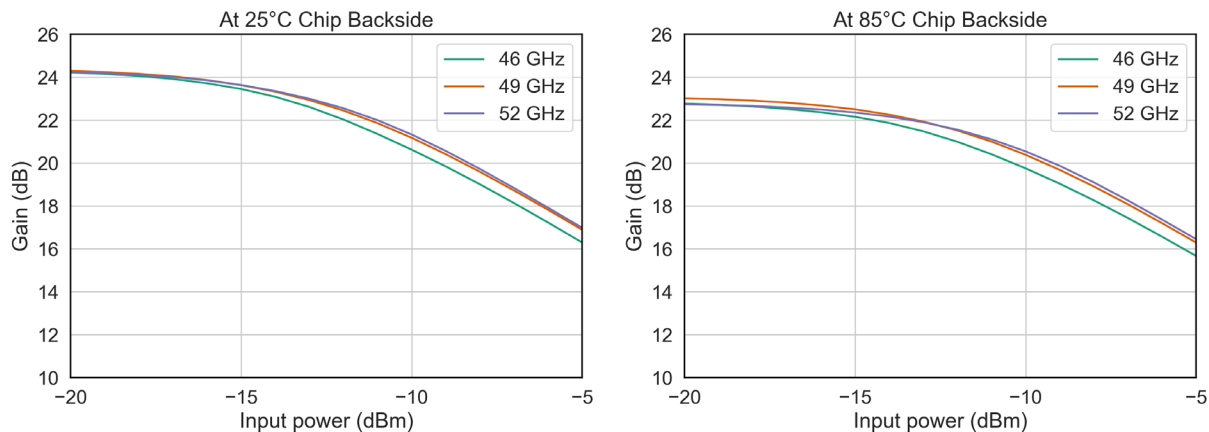


### Typical on Board Measurements

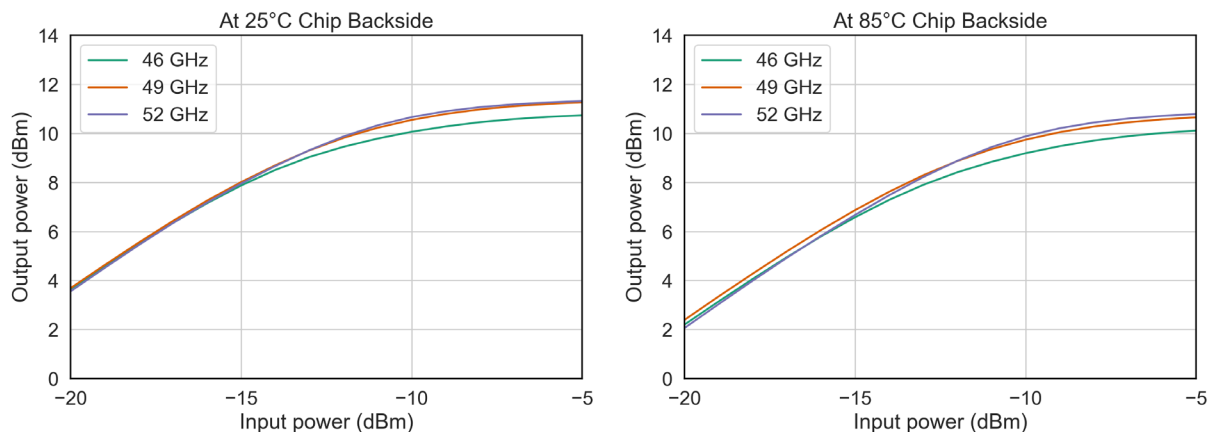
Test conditions :  $T_{backside} = +25^{\circ}\text{C}/85^{\circ}\text{C}$ ,  $V_d = 3.3\text{V}$ ,  $I_d = 55\text{mA}$

Board losses are de-embedded. Measurements are given in the die access plans.

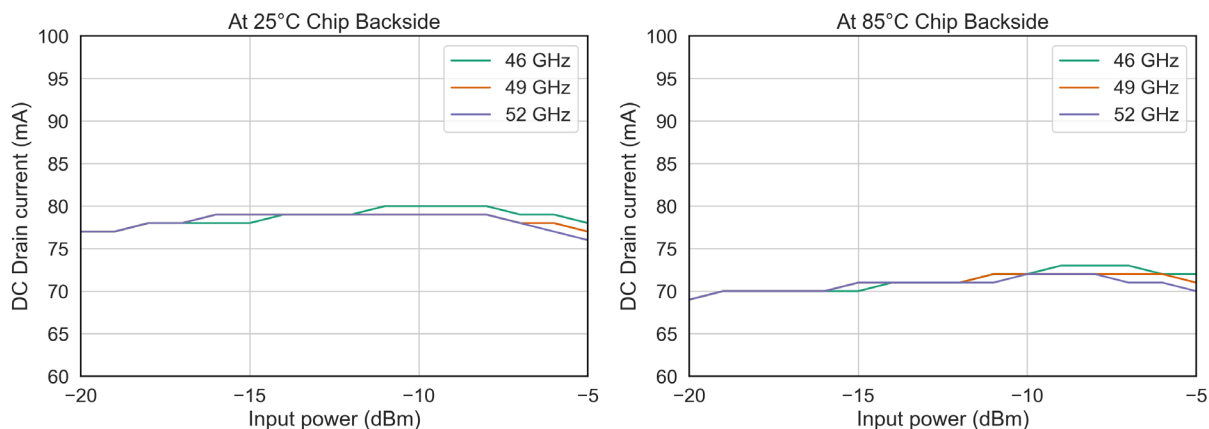
#### Gain vs. Input Power & Frequency



#### Output Power vs. Input Power & Frequency



#### Drain Current vs. Input Power & Frequency

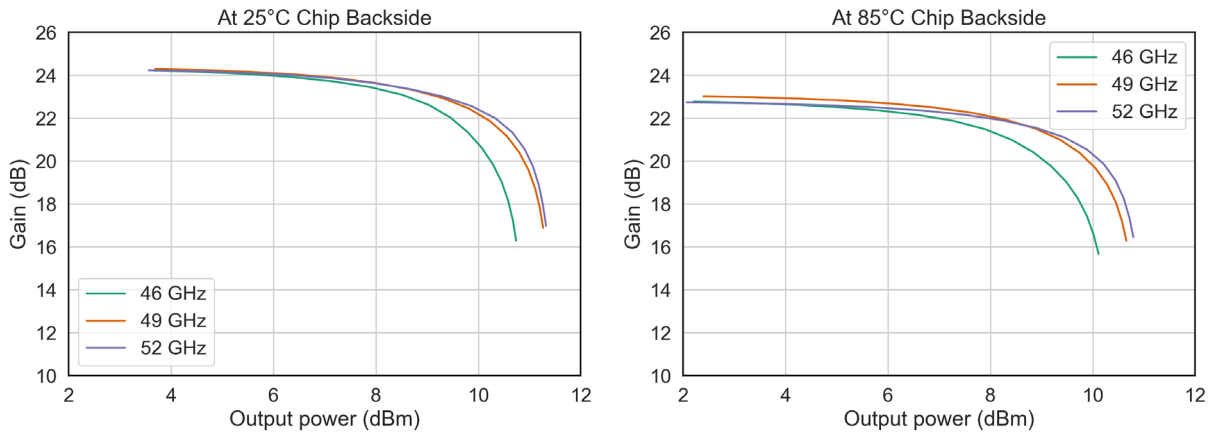


## Typical on Board Measurements

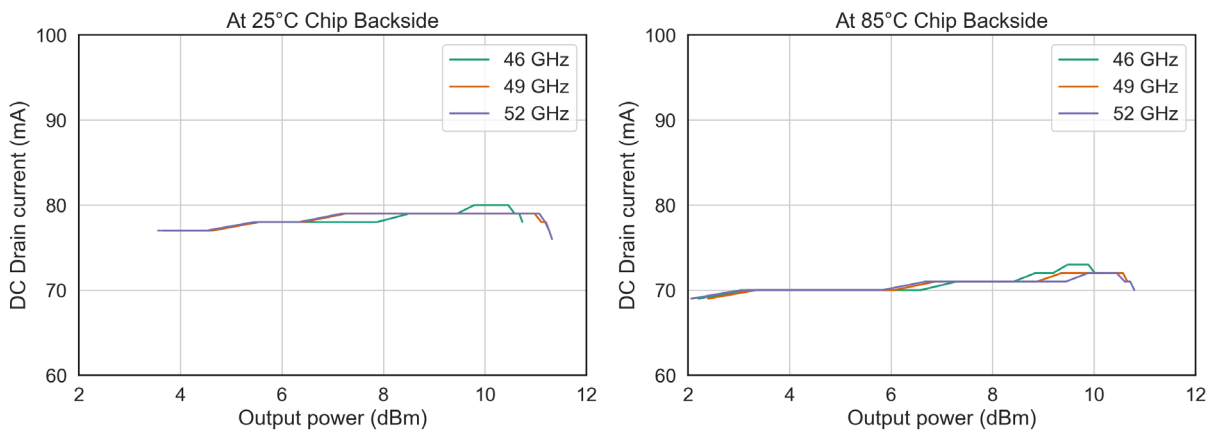
**Test conditions :**  $T_{\text{backside}} = +25^{\circ}\text{C}/85^{\circ}\text{C}$ ,  $V_d = 3.3\text{V}$ ,  $I_d = 55\text{mA}$

Board losses are de-embedded. Measurements are given in the die access plans.

### Gain vs. Output Power & Frequency



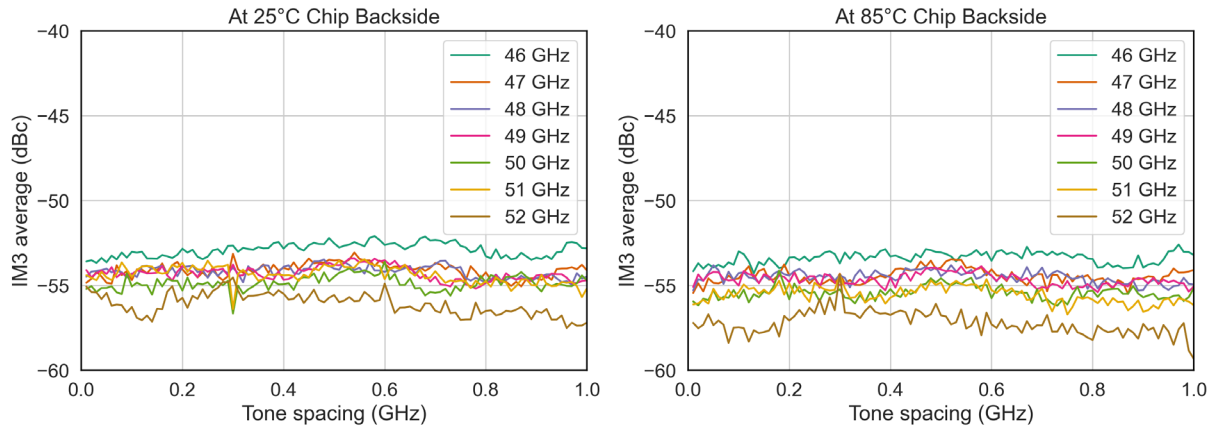
### Drain Current vs. Output Power & Frequency



**Typical Board Measurements**

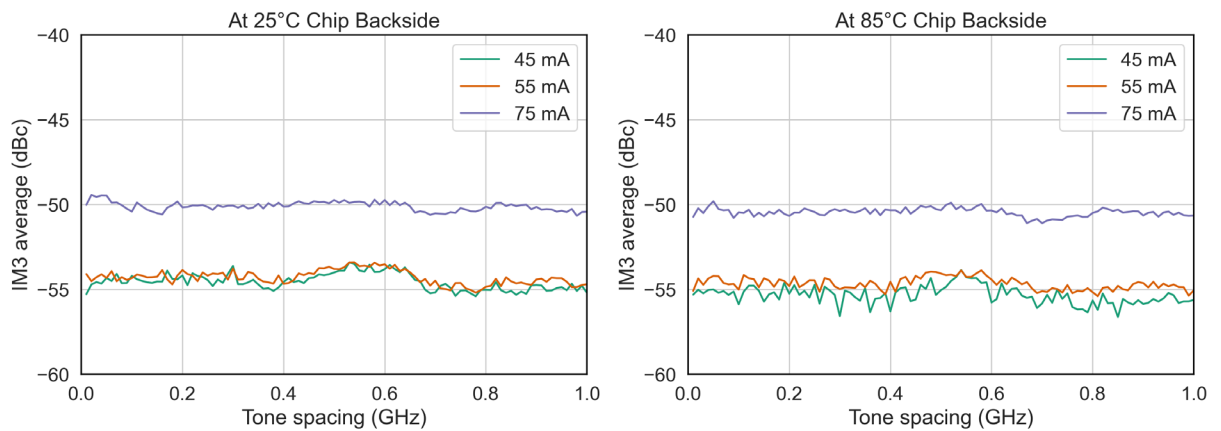
**Test conditions :** CW dual tones,  $V_d = 3.3V$ ,  $I_{dq} = 55mA$ ,  $P_{in}/tone = -30dBm$ ,  $T_{backside} = +25^{\circ}C/85^{\circ}C$

**IMD3 vs. Tone Spacing & Frequency**



**Test conditions :** CW dual tones,  $V_d = 3.3V$ ,  $F_c = 49GHz$ ,  $P_{in}/tone = -30dBm$ ,  $T_{backside} = +25^{\circ}C/85^{\circ}C$

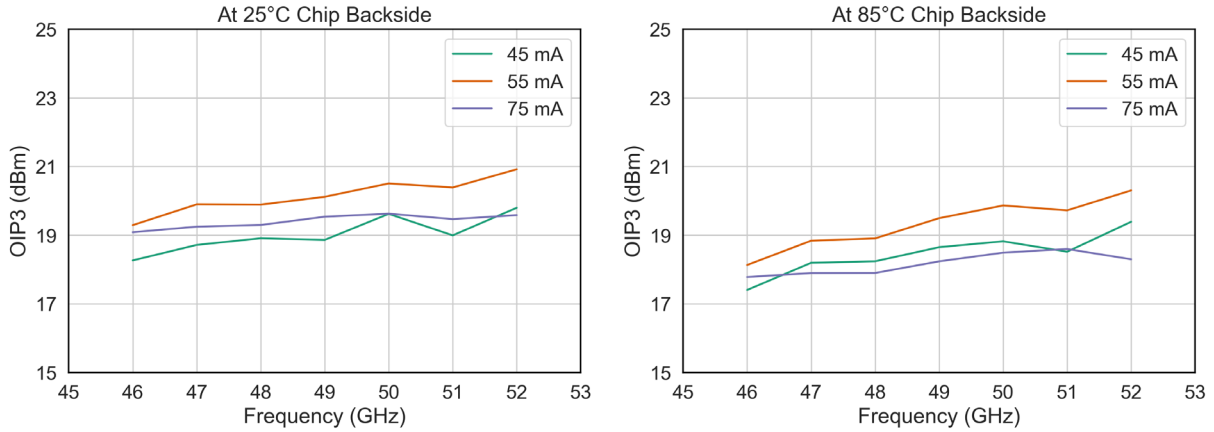
**IMD3 vs. Tone Spacing & Drain Current**



## Typical Board Measurements

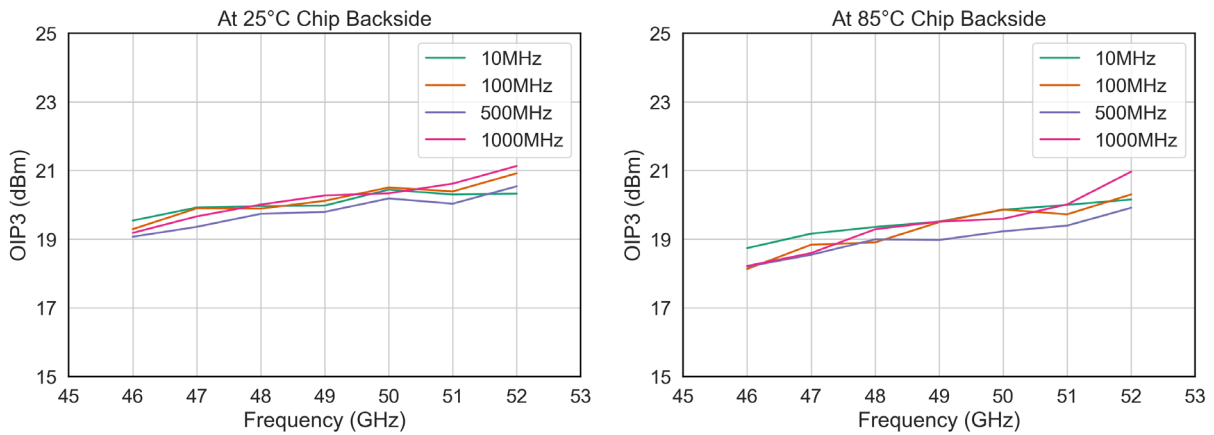
**Test conditions :** CW dual tones,  $V_d = 3.3V$ ,  $I_{dq} = 45/55/75mA$ ,  $\Delta f = 10MHz$ ,  $P_{in}/tone = -30dBm$ ,

### OIP3 vs. Frequency & Quiescent Drain Current



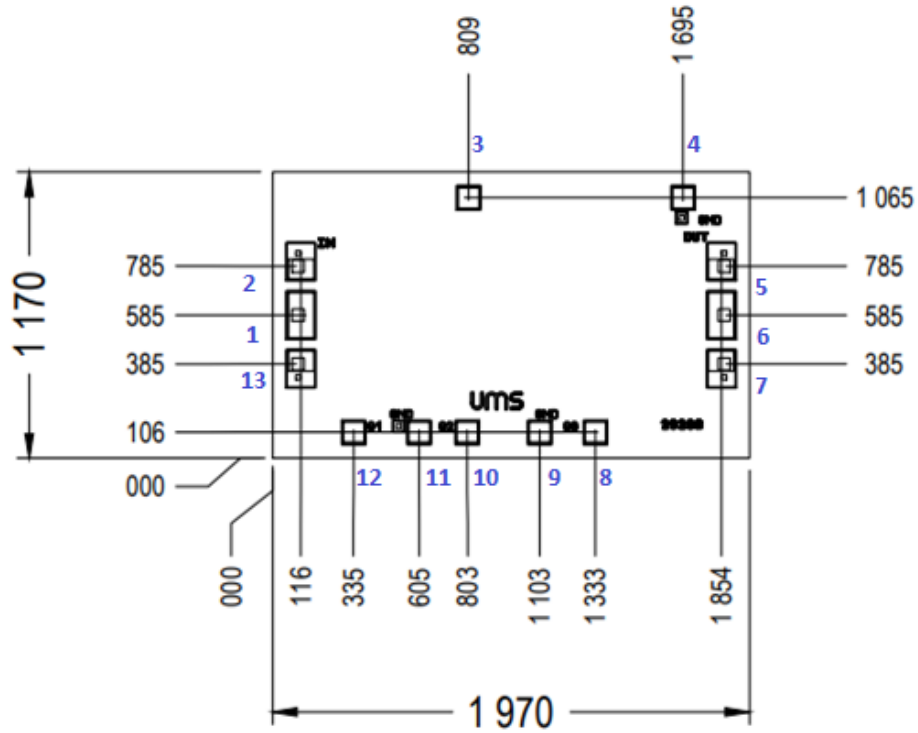
**Test conditions :** CW dual tones,  $V_d = 3.3V$ ,  $I_{dq} = 55mA$ ,  $\Delta f = 10/100/500/1000MHz$ ,  $P_{in}/tone = -30dBm$

### OIP3 vs. Frequency & Tone spacing



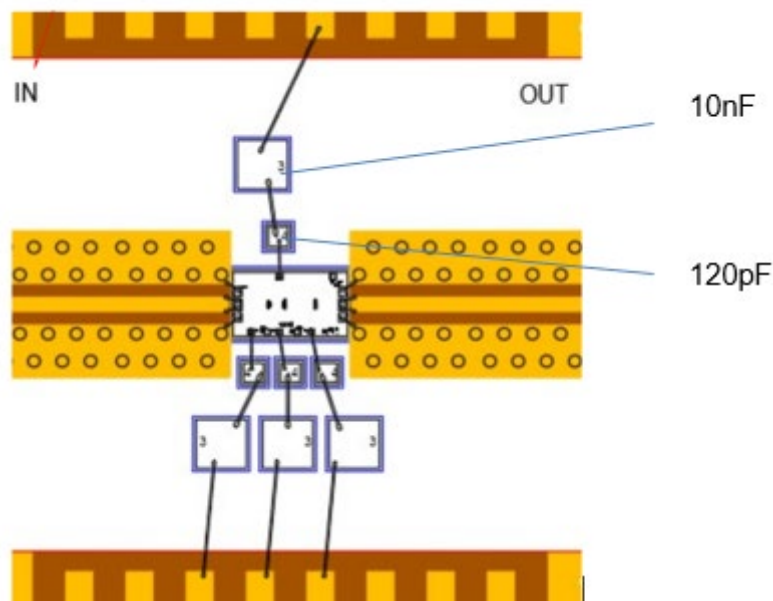
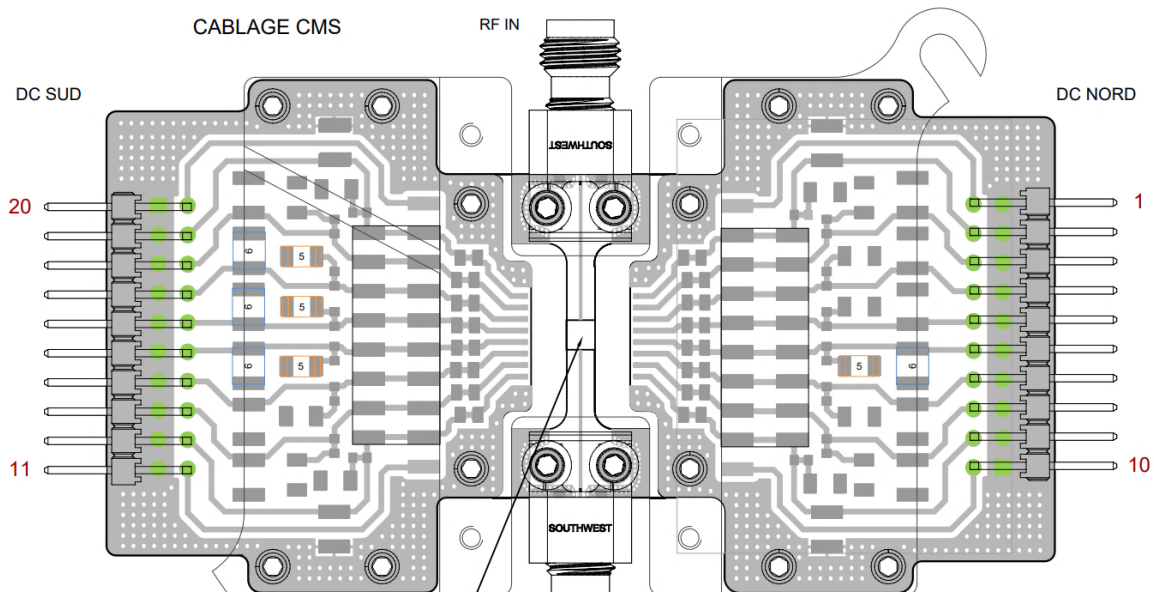
**Mechanical data**

Chip thickness: 70µm  
 Chip size: 1970µm x 1170µm ±35µm  
 All dimensions are in micrometers



PAD Number	Name	Description	Pad size (BCB Opening)
1	RF IN	Input RF port	186µm x 105µm
3	D	DC Drain voltage all stages	86µm x 83µm
6	RF OUT	Output RF port	186µm x 105µm
8	G3	DC Gate voltage 3 <sup>rd</sup> stage	86µm x 83µm
10	G2	DC Gate voltage 2 <sup>nd</sup> stage	86µm x 83µm
12	G1	DC Gate voltage 1 <sup>st</sup> stage	86µm x 83µm
4,9,11	GND	Ground DC	86µm x 83µm
2,5,7,13	GND	Ground RF	105 µm x 82 µm

## Evaluation board



Total of 4 levels of decoupling capacitors have been used, 2 levels on the tab and 2 levels on the board. The first level is composed of 120pF chip capacitors, the second level is composed of 10nF chip capacitors and the third level is composed of 100nF capacitors and 1µF for the last. The first two levels should be as close as possible to the chip.

## **Recommended reflow process assembly**

Refer to the application note AN0001 available at <http://www.ums-rf.com> for die attach.

## **Recommended environmental management**

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <http://www.ums-rf.com>.

## **Recommended ESD management**

Refer to the application note AN0020 available at <http://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS die products.

## **Recommended Evaluation board assembly**

Refer to the application note AN0030 available at <https://www.ums-rf.com> for the description of Evaluation Board and recommendations for this UMS die product.

Ordering request reference

Chip form:

CHA2353-99F/00

Information furnished is believed to be accurate and reliable. However **United Monolithic Semiconductors S.A.S.** assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of **United Monolithic Semiconductors S.A.S.**. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied. **United Monolithic Semiconductors S.A.S.** products are not authorised for use as critical components in life support devices or systems without express written approval from **United Monolithic Semiconductors S.A.S.**